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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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VEC2315

Power MOSFET –60V, 137mΩ, –2.5A, Dual P-Channel

This Power MOSFET is produced using ON Semiconductor's trench technology, which is specifically designed to minimize gate charge and low on resistance. This device is suitable for applications with low gate charge driving or low on resistance requirements.

Features

- Low On-Resistance
- 4V drive
- Low-Profile Package
- ESD Diode-Protected Gate
- Pb-Free, Halogen Free and RoHS compliance

Typical Applications

- Motor Driver

SPECIFICATIONS

ABSOLUTE MAXIMUM RATING at Ta = 25°C (Note 1)

Parameter	Symbol	Value	Unit
Drain to Source Voltage	V _{DSS}	–60	V
Gate to Source Voltage	V _{GSS}	±20	V
Drain Current (DC)	I _D	–2.5	A
Drain Current (Pulse) PW ≤ 10μs, duty cycle ≤ 1%	I _{DP}	–10	A
Power Dissipation When mounted on ceramic substrate (900mm ² × 0.8mm) 1unit	P _D	0.9	W
Total Dissipation When mounted on ceramic substrate (900mm ² × 0.8mm)	P _T	1.0	W
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	–55 to +150	°C

Note 1 : Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Value	Unit
Junction to Ambient When mounted on ceramic substrate (900mm ² × 0.8mm) 1unit	R _{θJA}	138.8	°C/W

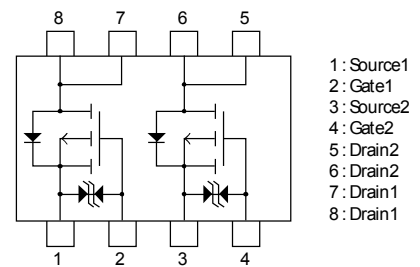


ON Semiconductor[®]

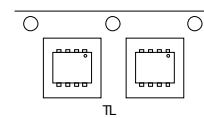
www.onsemi.com

V _{DSS}	R _{DS(on)} Max	I _D Max
–60V	137mΩ@ –10V	–2.5A
	180mΩ@ –4.5V	
	194mΩ@ –4V	

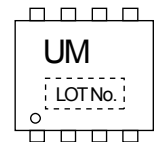
ELECTRICAL CONNECTION P-Channel



PACKING TYPE : TL



MARKING



ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

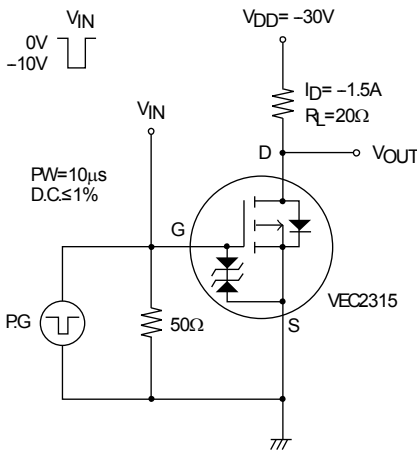
VEC2315

ELECTRICAL CHARACTERISTICS at Ta = 25°C (Note 2)

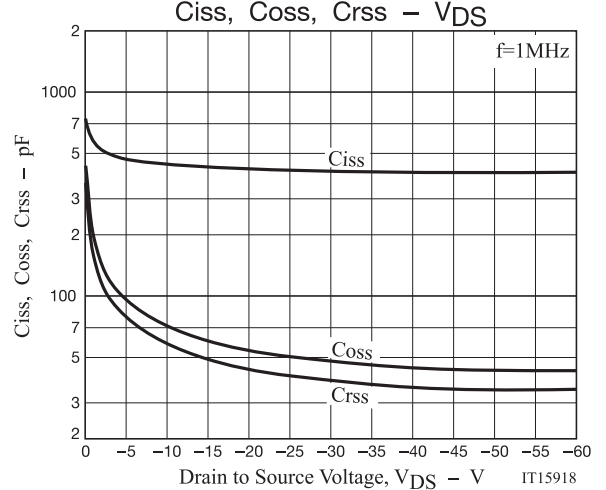
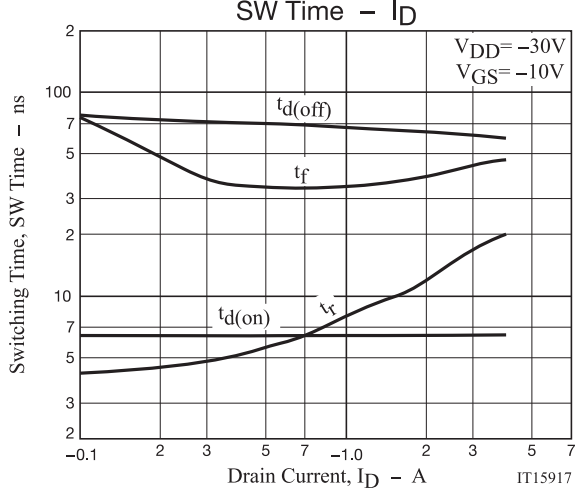
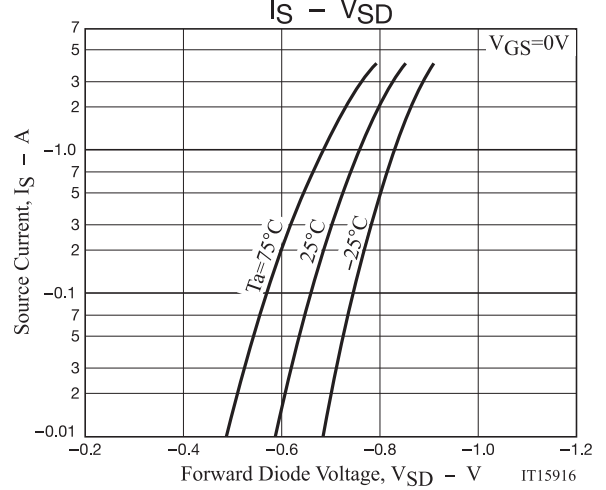
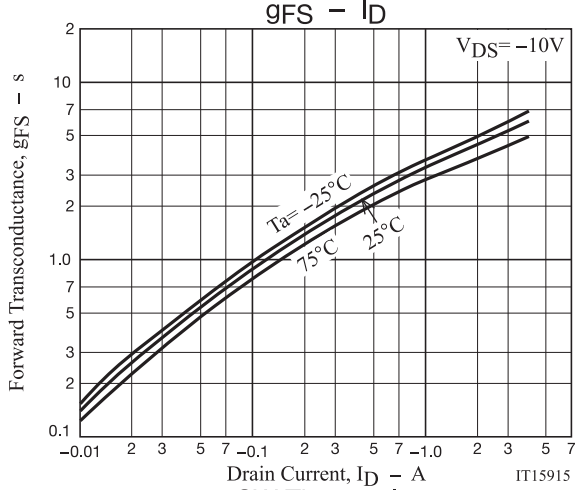
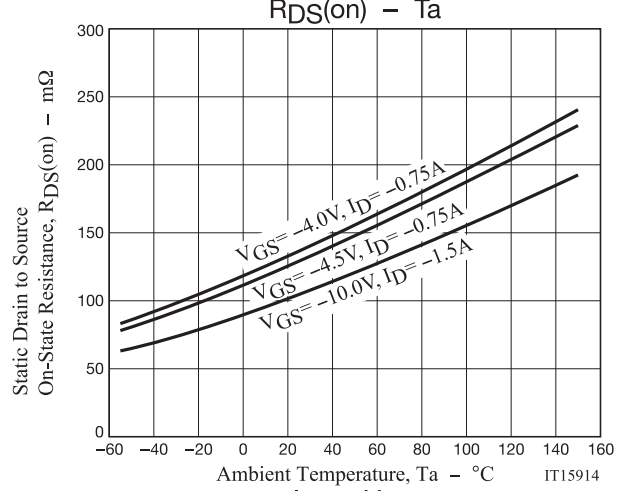
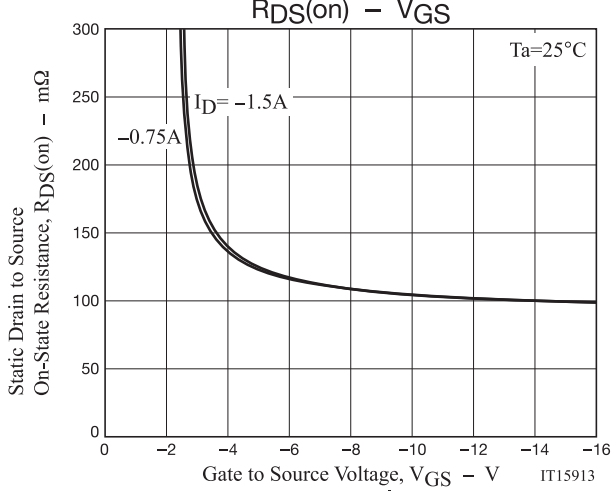
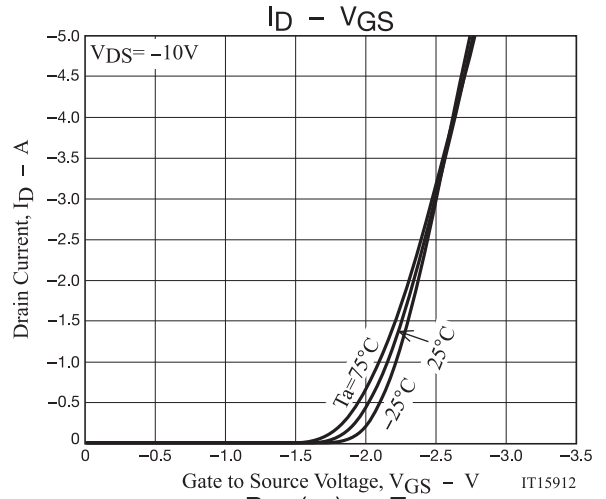
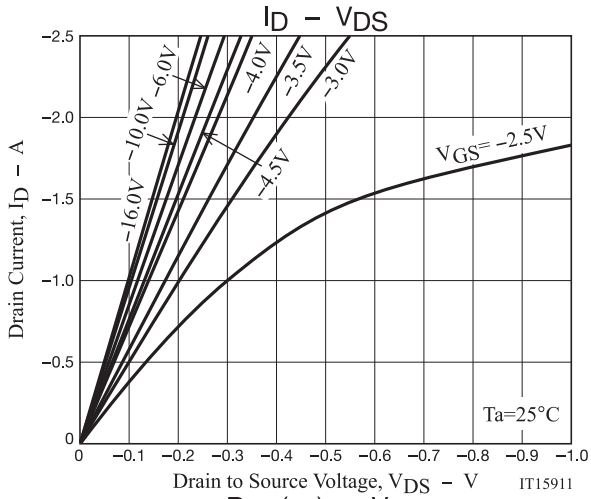
Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	V(BR)DSS	I _D =-1mA, V _{GS} =0V	-60			V
Zero-Gate Voltage Drain Current	I _{DSS}	V _{DS} =-60V, V _{GS} =0V			-1	μA
Gate to Source Leakage Current	I _{GSS}	V _{GS} =±16V, V _{DS} =0V			±10	μA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =-10V, I _D =-1mA	-1.2		-2.6	V
Forward Transconductance	g _{FS}	V _{DS} =-10V, I _D =-1.5A		3.9		S
Static Drain to Source On-State Resistance	R _{DS(on)1}	I _D =-1.5A, V _{GS} =-10V		105	137	mΩ
	R _{DS(on)2}	I _D =-0.75A, V _{GS} =-4.5V		128	180	mΩ
	R _{DS(on)3}	I _D =-0.75A, V _{GS} =-4V		138	194	mΩ
Input Capacitance	C _{iss}	V _{DS} =-20V, f=1MHz		420		pF
Output Capacitance	C _{oss}			54		pF
Reverse Transfer Capacitance	C _{rss}			44		pF
Turn-ON Delay Time	t _{d(on)}	See specified Test Circuit		6.4		ns
Rise Time	t _r			9.8		ns
Turn-OFF Delay Time	t _{d(off)}			65		ns
Fall Time	t _f			36		ns
Total Gate Charge	Q _g				11	
Gate to Source Charge	Q _{gs}	V _{DS} =-30V, V _{GS} =-10V, I _D =-2.5A		1.4		nC
Gate to Drain "Miller" Charge	Q _{gd}			2		nC
Forward Diode Voltage	V _{SD}	I _S =-2.5A, V _{GS} =0V		-0.83	-1.2	V

Note 2 : Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

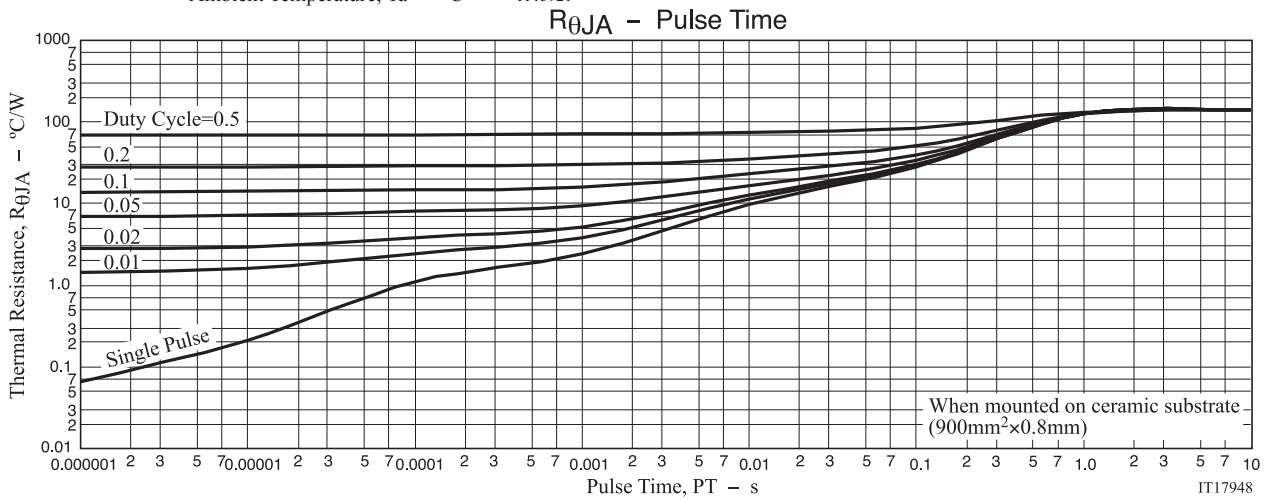
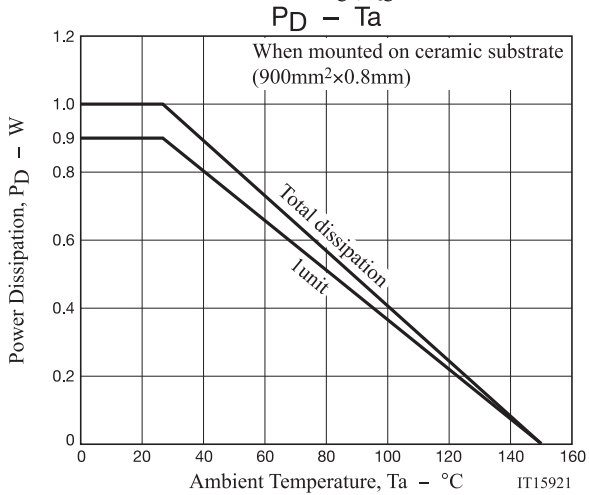
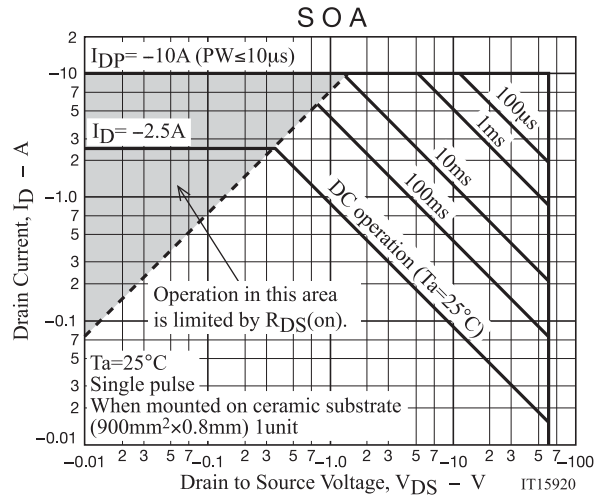
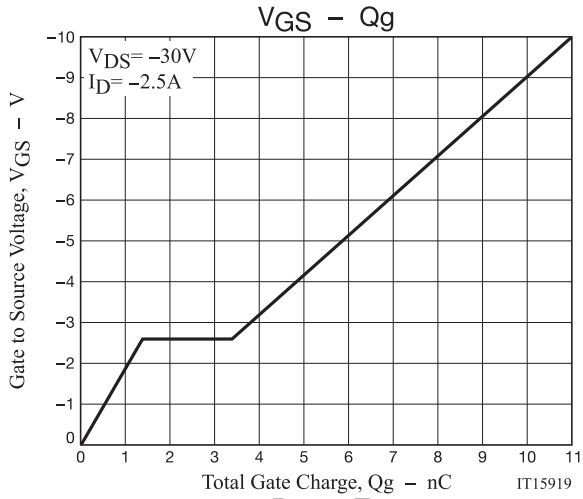
Switching Time Test Circuit



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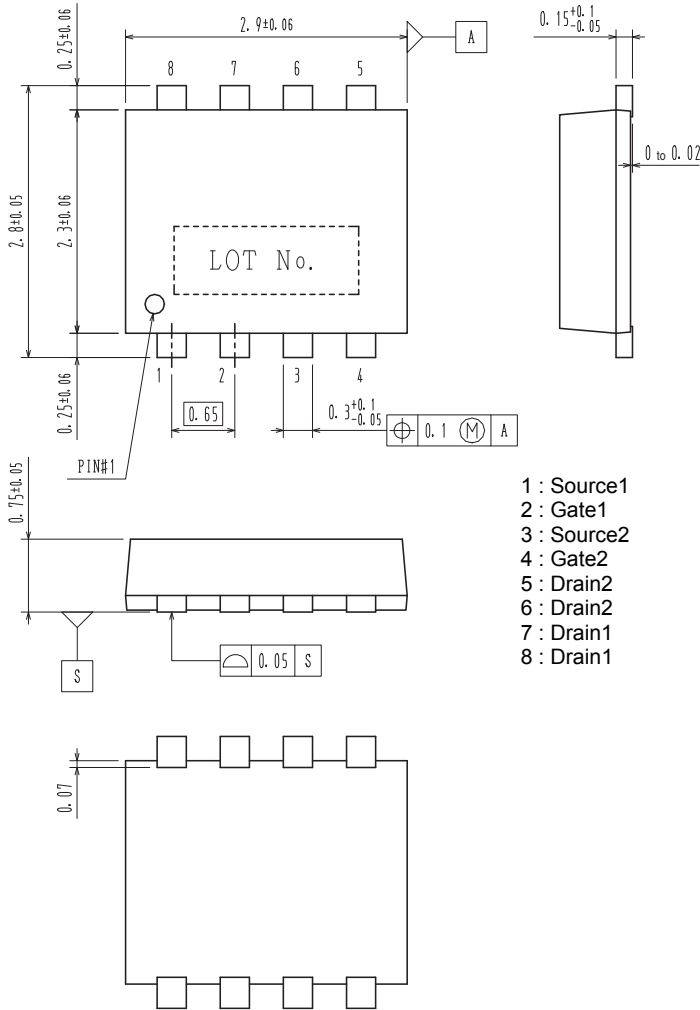


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PACKAGE DIMENSIONS

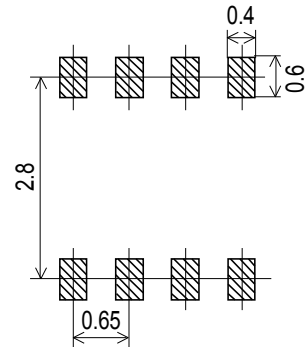
unit : mm

SOT-28FL / VEC8
CASE 318AH
ISSUE O



- 1 : Source1
- 2 : Gate1
- 3 : Source2
- 4 : Gate2
- 5 : Drain2
- 6 : Drain2
- 7 : Drain1
- 8 : Drain1

Recommended Soldering Footprint



ORDERING INFORMATION

Device	Marking	Package	Shipping (Qty / Packing)
VEC2315-TL-H	UM	SOT-28FL / VEC8 (Pb-Free / Halogen Free)	3,000 / Tape & Reel
VEC2315-TL-W			

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub_link/Collateral/BRD8011-D.PDF

Note on usage : Since the VEC2315 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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